<table>
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<th>Feature</th>
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| TUV-certified probing environment                                      | • Enclosure for operator safety  
• Interlock connection for test instruments  
• Regulatory-approved high-voltage and high-current cables and connectors                                                                                                     |
| High-stability microscope mount                                       | • Manual or programmable  
• Gross Z lift with repeatable focus for easy access to probes                                                                                                                                             |
| Connection panels                                                     | • Coaxial, triaxial, and pin jack feed-throughs available  
• Limit cable strain and motion for measurement stability  
• Instrument stays connected to back of panel  
• Probe connection made at front of panel  
• Simple to re-arrange cabling when needed                                                                                  |
| MicroChamber®                                                          | • EMI-shielding for low-noise measurements  
• Environmentally sealed for moisture-free, low-temperature measurements  
• Low volume for the fastest purge  
• Light-tight to eliminate the need for a dark box                                                                       |
| TopHat®                                                                | • New TopHat covers for easier and higher-accuracy probe setup  
• Allows full access to positioners and microscope at any temperature  
• Allows probe adjustments without exposing wafer and chamber to external environment                                        |
| AttoGuard®                                                             | • Extends instrument guard to completely surround wafer  
• Makes the station invisible to the instrument  
• Extremely low capacitance and leakage characteristics  
• Fast setting times                                                                                                           |
| PureLine® technology                                                   | • Enhanced EMI-shielding  
• Ideal for low-level IV and CV measurements                                                                                                                                                    |
| Platen lift                                                            | • Easy and safe contact and separate function for probe cards and positioners  
• Available micrometer adjustment to set probe card contact                                                                                                                               |
| MicroChamber access door                                               | • Anti-blocking door to protect wafers at cold temperatures  
• Full-width for easy access to wafers and cal substrates  
• Hardware interlock to protect user from hazardous chuck bias voltage                                                        |
| Rollout stage                                                          | • Full wafer access for safe and easy loading  
• Maintains chuck integrity without contaminating layers  
• Easy access to calibration substrates on auxiliary chucks  
• New LIFT pin technology for fast manual handling/unload of hot wafers                                                       |
| eVue® IV Digital Imaging System                                        | • Fast probe set-up with wide field-of-view and single objective in MicroChamber  
• Easy navigation with multiple live video views of probes and wafer  
• New high-speed focus system for faster and accurate die stepping  
• New safety features for probes and usability                                                                           |
| Velox® probe station control software                                  | • Innovative operating software for advanced probe operation, temperature control,  
• Z-profiling and stepping  
• Wiper mapping, automated wafer alignment, and auto XY and theta correction for sub-micron stepping                                      |
| Probes / Probe cards                                                   | • High voltage (3 kV / 10 kV)  
• High current (300 A)  
• Low leakage  
• High voltage anti-arcing probe card                                                                                         |
| Contact Intelligence™ Technology                                       | • Integrated HTS (High Thermal Stability) reduces probe drift and thermal soak time  
• Optional VueTrack™ reduces thermal soak time (faster time to data)  
• Enables unattended test over multiple temperatures                                                                         |
| Auxiliary chucks                                                      | • High voltage 10 kV compatible multi-purpose mounts for substrates (cleaning, contact)  
• Automated probe cleaning capabilities                                                                                          |
| Manual mode stage control                                             | • Intuitive manual chuck XY stage controls in semi-automatic engineering mode  
• Safe mode: automatically disables manual controls in automation mode                                                                                                           |
| Precision 200 mm motorized wafer stage                                | • New user-selectable performance modes for standard, fast and high accuracy  
• Increased test throughput with up to 100 mm/sec speed  
• High reliability 24/7 operation                                                                                               |
| Scalable system                                                       | • In-field upgradable wafer loading and automation  
• Add test accuracy improvements for increased test performance                                                               |
| Patented TESLA chuck technologies                                      | • HV FemtoGuard® (3kV triaxial / 10kV coaxial) and low leakage  
• Gold-plated MicroVac(TM) surface for minimal chuck-to-wafer contact resistance  
• 3kV coaxial and high-current (600A) options  
• Wide range of temperature options from -55°C to 300°C and higher  
• Spessially chuck for +400°C, and low inductance / Cappmo for UIS unclamped (resistance switching)                                      |
| Compact small footprint                                               | • Integrated vibration isolation for reliable small pad probing  
• Integrated system electronics with power loss wafer safety protection                                                     |